## AMENDMENTS TO THE CLAIMS

1. (currently amended) A method for forming a gate structure for a semiconductor transistor, the <u>method</u> comprising:

forming a lower polysilicon region on a gate dielectric layer; implanting said lower polysilicon region with a dopant at a first dopant concentration;

forming a conductive barrier layer upon said lower polysilicon region; forming an upper polysilicon region upon said conductive barrier layer;

implanting said upper polysilicon region with dopant at a second dopant concentration, said second concentration being different than said first concentration.

- 2. (original) The method of claim 1, further comprising forming a silicide layer on said upper polysilicon region.
- 3. (original) The method of claim 1, wherein said conductive barrier is selected from the group of: tungsten nitride (WN), tantalum nitride (TaN), titanium nitride (TiN), tungsten silicon nitride (WSiN), tantalum silicon nitride (TaSiN), aluminum titanium nitride (AlTiN), titanium silicide (TiSi), quantum conductive semi-insulating barriers, and combinations comprising at least one of the foregoing.
- 4. (original) The method of claim 1, wherein said lower polysilicon region comprises silicon germanium carbon (SiGeC).
- 5. (original) The method of claim 1, wherein said lower polysilicon region is doped at a concentration of about  $1 \times 10^{21}$  atoms/cm<sup>3</sup>, and said upper polysilicon region is doped at a concentration of about  $3 \times 10^{20}$  atoms/cm<sup>3</sup>.

6. (original) The method of claim 1, wherein said lower polysilicon region is formed by:

defining a polysilicon block on said gate dielectric layer;
forming a sacrificial layer over said gate dielectric layer and said
polysilicon block;

planarizing said sacrificial layer down to the top of said polysilicon block;

recessing said polysilicon block below the top of the planarized sacrificial layer.

- 7. (new) The method of claim 1, wherein said upper polysilicon region is formed directly upon a top surface of said conductive barrier layer.
- 8. (new) The method of claim 1, wherein said second concentration is less than said first concentration.